



IECQ Certificate of Conformity

Capability

IECQ Certificate No.:	IECQ-C BSI 15.0012	Issue No.:	2	Status:	Current
Supersedes:	IECQ-C BSI 15.0012 Issue 1	Issue Date:	2018/11/09	Org Issue:	2009/04/15
CB Reference No.:	028/ICA Issue 4	Expiration:	2021/11/30		

Graphic Plc

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United Kingdom

The organization has developed and implemented procedures and related processes which have been assessed by the IECQ Certification Body issuing this certificate and found to comply with the applicable requirements of the IECQ Approved Component Scheme "Capability Certification" which is in accordance with the Basic Rules IECQ 01 "Rules of Procedure", IECQ 03-1 "IECQ General Requirements for all Schemes" and IECQ 03-3 Annex D "IECQ Approved Components Scheme" of the IEC Quality Assessment System for Electronic Component (IECQ), and in respect of standard(s) or specification(s):

- IPC-6011 {July 1996} Generic Performance Specification for Printed Boards
- IPC-6012C {2010} Qualification and Performance Specification for Rigid Printed Boards
- IPC-6013B {January 2009} Qualification and Performance Specification for Flexible Printed Boards

Process Manual Reference: **GE/CM-IPC**

Details of Components/Assemblies/Materials:

Printed Wiring Boards

-- Attached Schedule: 028_ICA Issue 2 scope.pdf --

Issued by the Certification Body (CB): **BSI**

Kitemark Court, Davy Avenue
Knowlhill, Milton Keynes MK5 8PP
United Kingdom

Authorized person:
Paul Turner

PT _____

bsi.



The validity of this certificate is maintained through on-going surveillance audits by the IECQ CB issuing this certificate.
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IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,
Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Conformity

Approved Component – Capability

IECQ Certificate No.: IECQ-C BSI 15.0012

CB Certificate No.: 028/ICA

Schedule Number: IECQ-C BSI 15.0012-S

Rev No.: 4

Revision Date: 2018/11/09

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Board Types:	Multilayer metal core boards with blind and/or buried vias (Type 6)	IPC 6012 Class 3*
	Multilayer metal core boards without blind or buried vias (Type 5) Multilayer boards with blind and/or buried vias (Type 4) Multilayer boards without blind or buried vias (Type 3) Double-Sided boards (Type 2) Single-Sided Boards (Type 1)	
	Multilayer rigid and flexible material combinations containing three or more conductive layers with plated through holes (Type 4) Multilayer flexible printed wiring containing three or more conductive layers with plated through holes, with or without stiffeners (Type 3) Double-sided flexible printed wiring containing two conductive layers with plated through holes, with or without stiffeners (Type 2) Single-sided flexible printed wiring containing one conductive layer, with or without stiffeners (Type 1)	IPC 6013 Class 3*

*With reduced sampling for structural integrity (micro-section) in accordance with IECQ OD 301

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Base Materials:	Epoxide Woven Glass (IPC-4101) Polyimide Film (IPC-4204)
Board Size:	609 mm x 457 mm Maximum
Conductors:	Minimum Width: 0.075mm Minimum Spacing: 0.09mm
Number of Layers:	30 Maximum
Plated-through hole diameter:	0.25 mm Minimum drilled
Aspect ratio:	8 : 1 Maximum
Finishes:	Hot Air Solder Levelled SnPb Electroplated SnPb Fused SnPb Electroless Nickel / Immersion Gold Immersion Tin Photoimagable liquid polymer solder resist Marking ink
Additional:	Bonded Heatsinks: Anodized Aluminium 2.5µm gold on 5µm nickel on copper 2.5µm gold on Copper Blind and Buried Via Holes

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